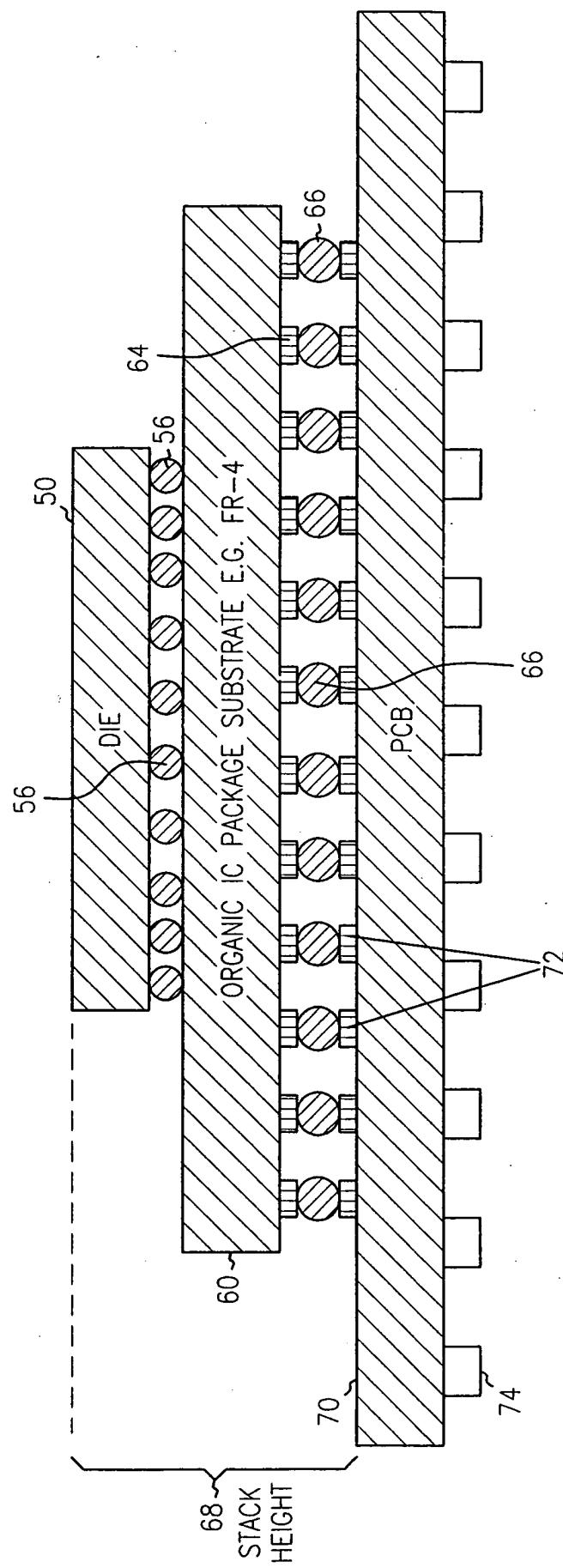


FIG. 1



**FIG. 2**  
(PRIOR ART)

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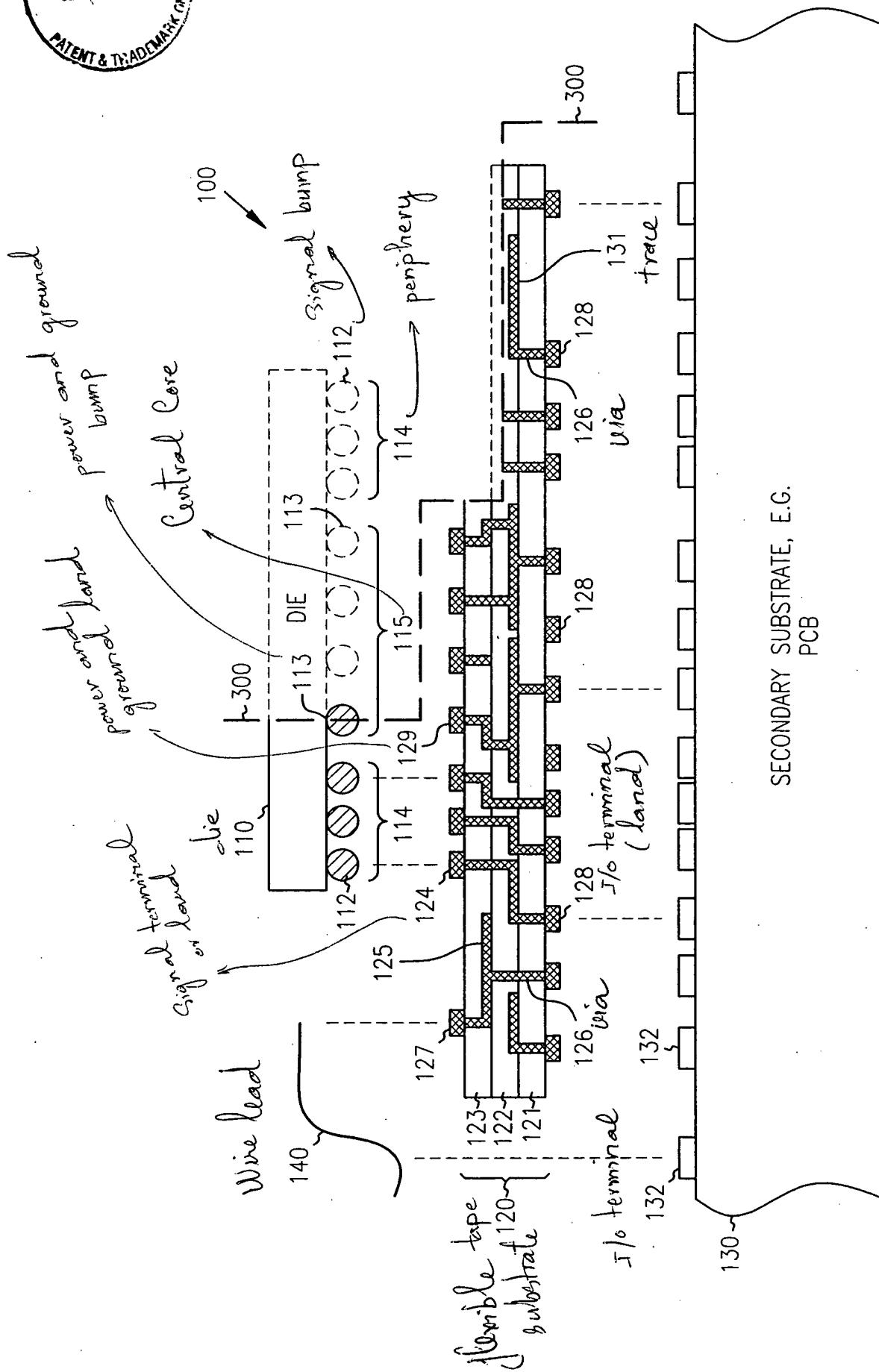


FIG. 3

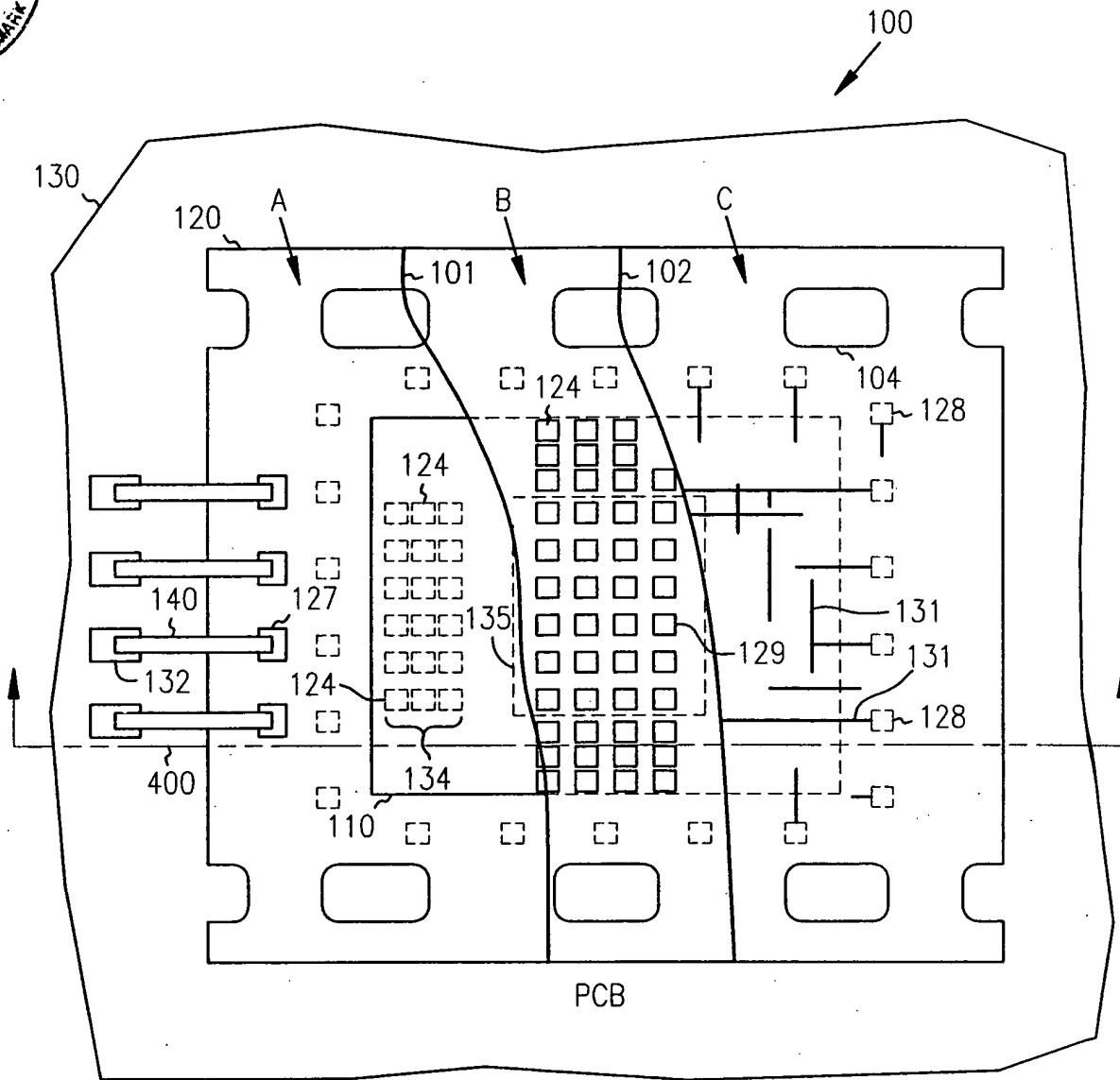


FIG. 4

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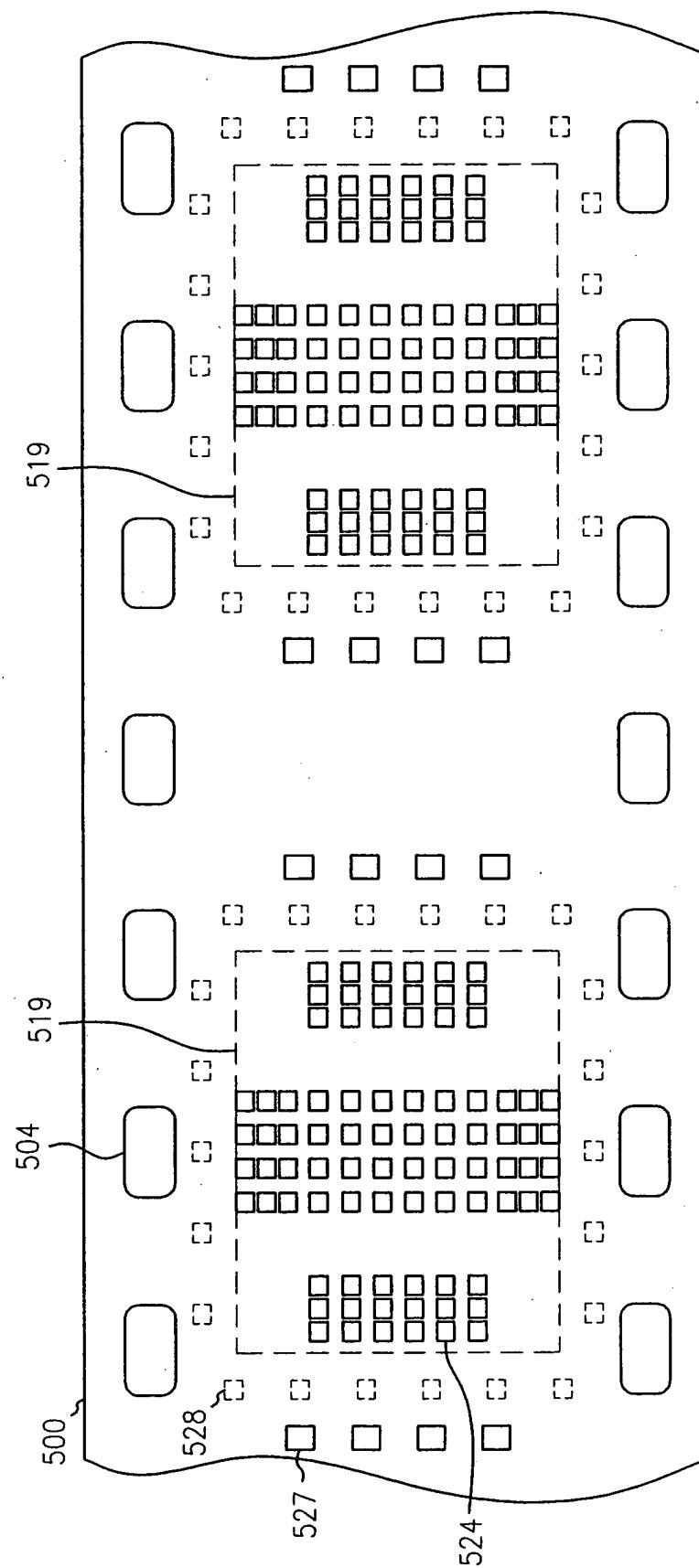
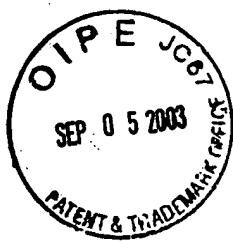


FIG. 5

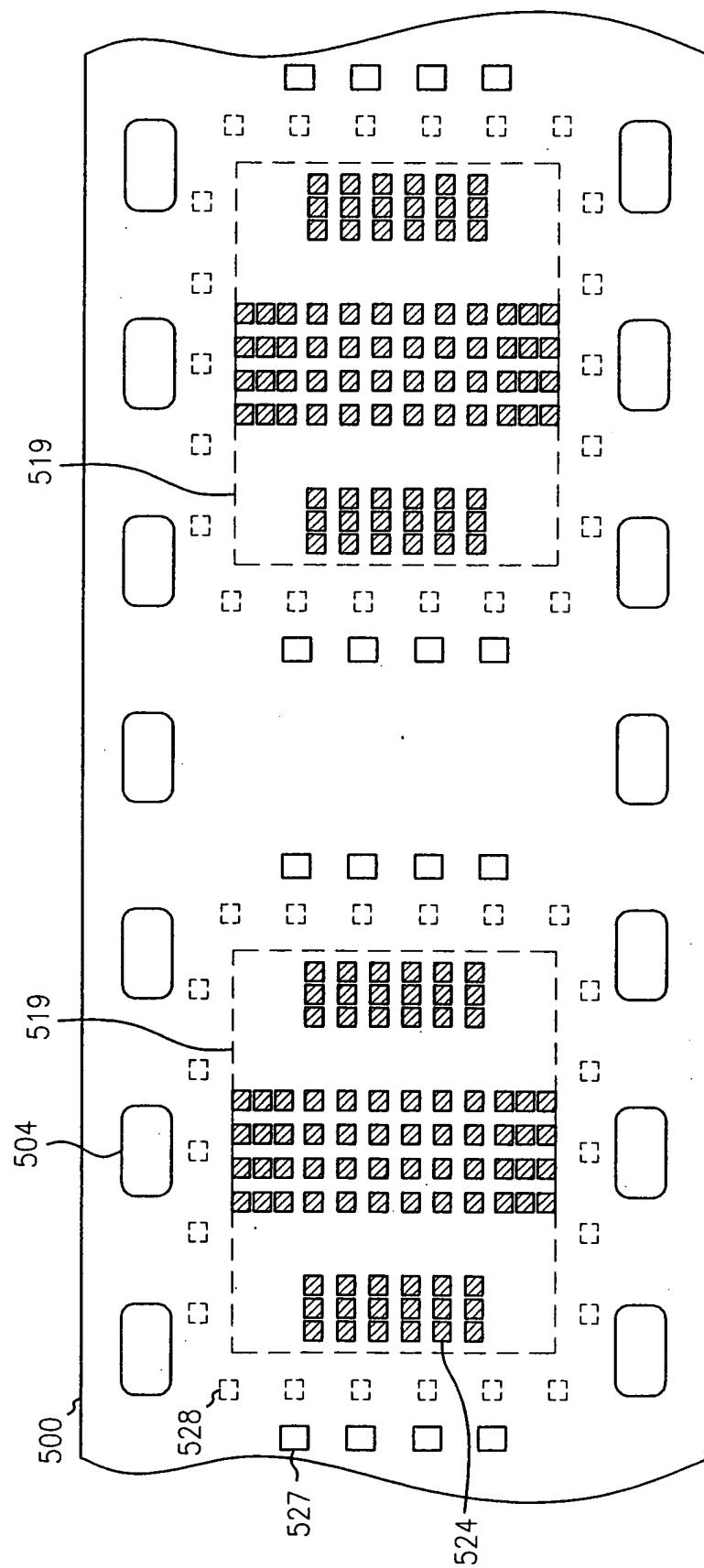


FIG. 6

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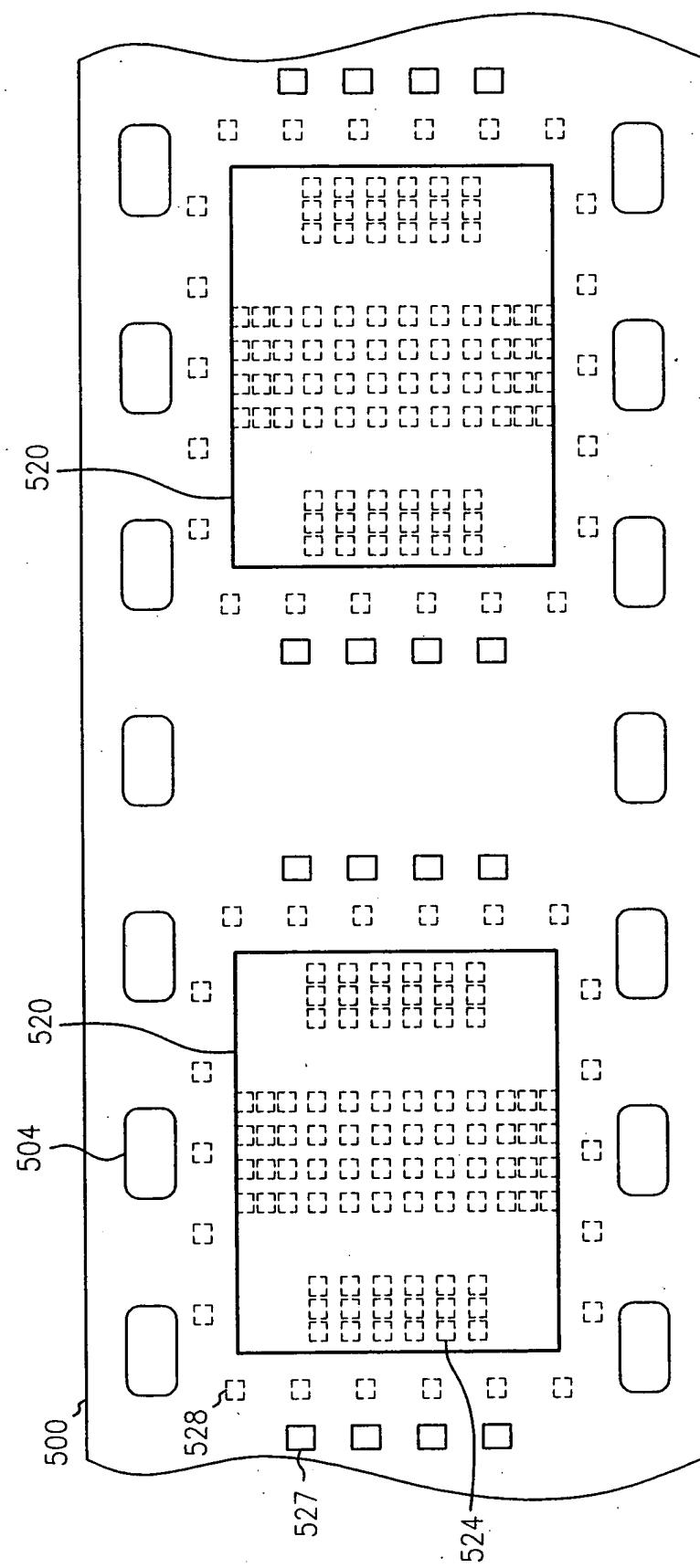


FIG. 7

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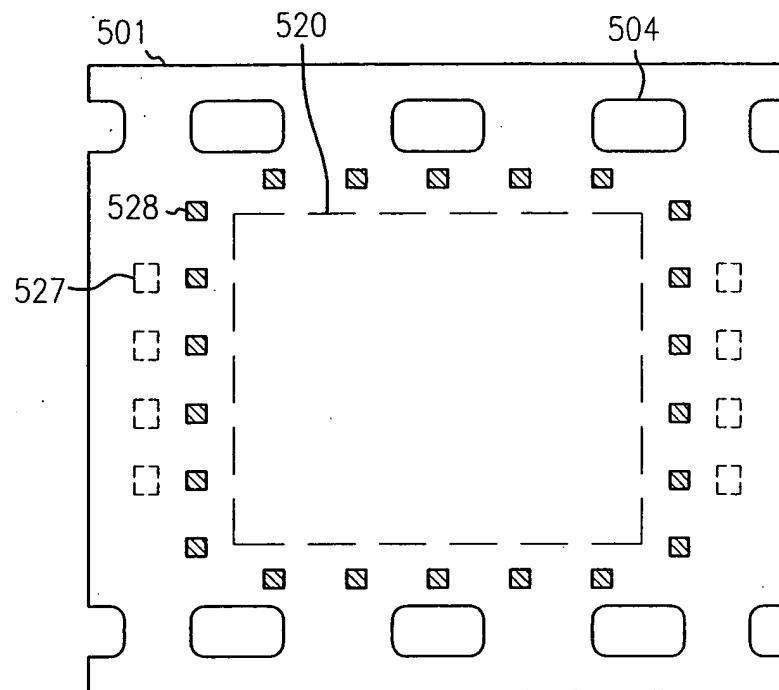


FIG. 8

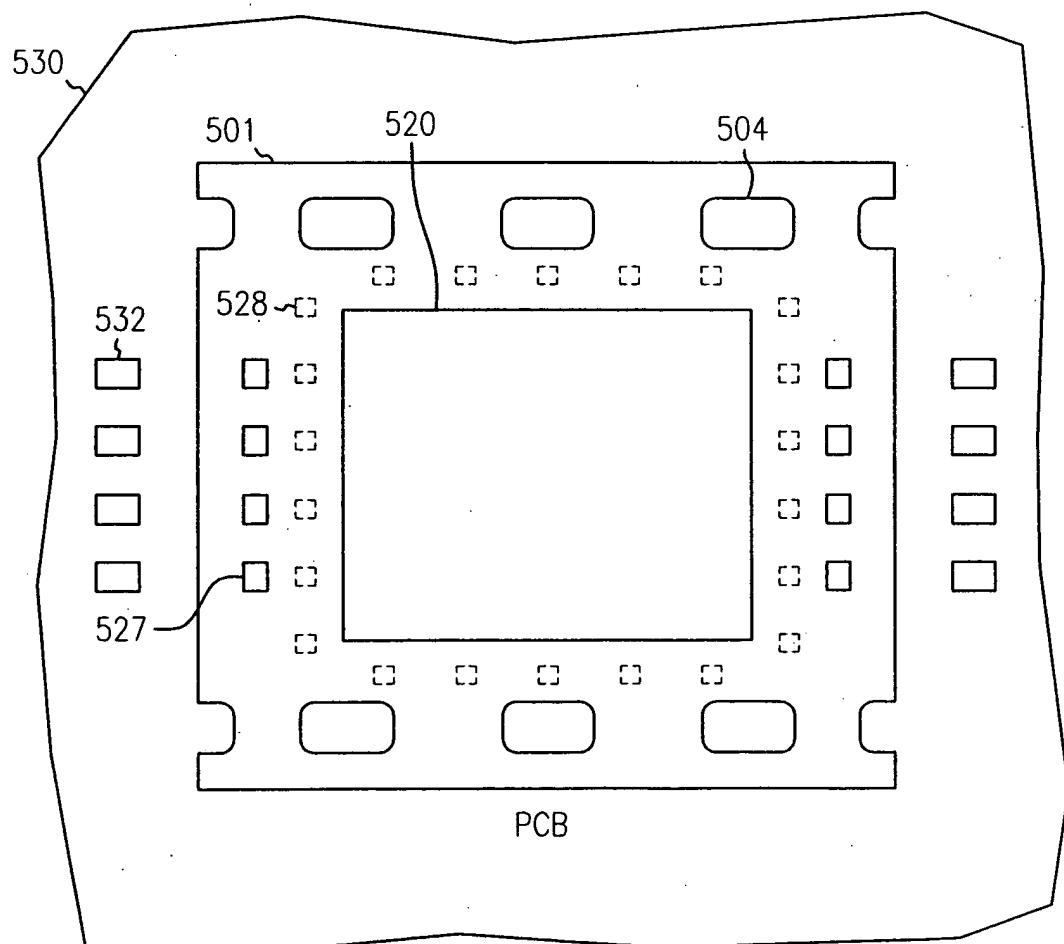


FIG. 9

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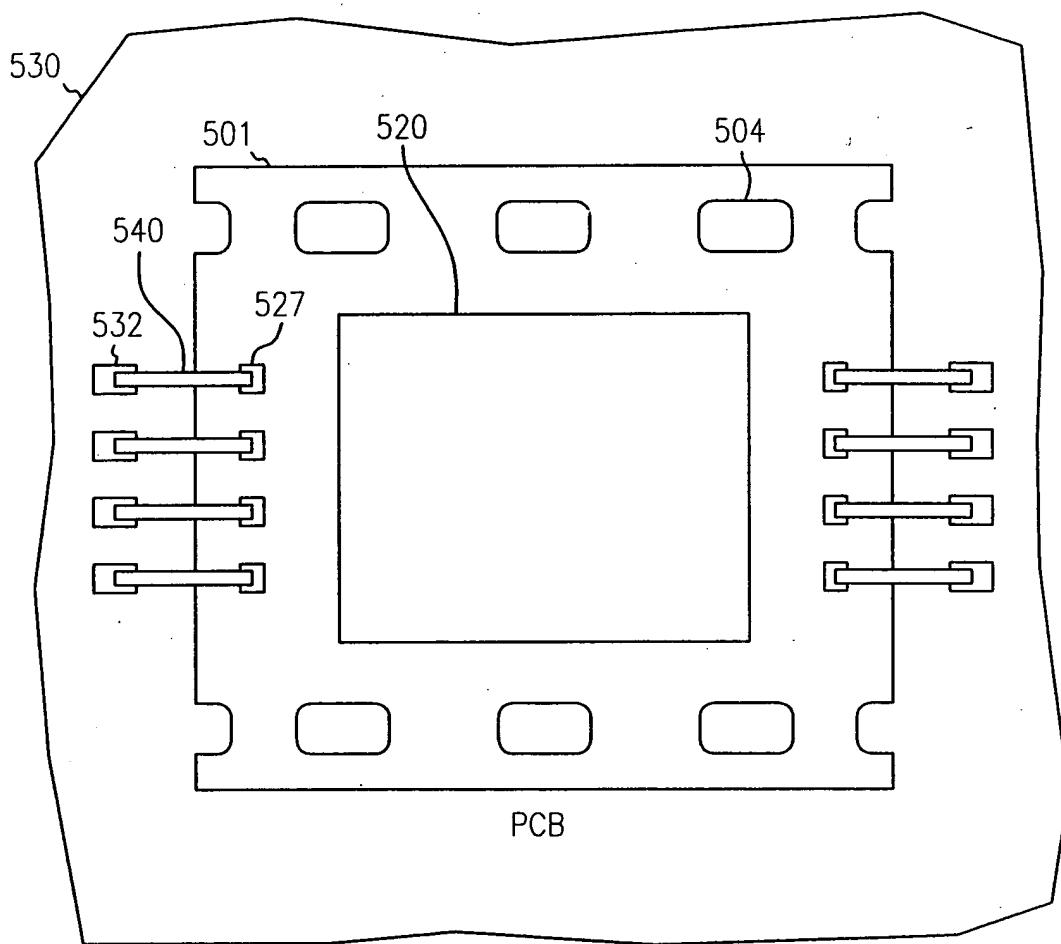


FIG. 10

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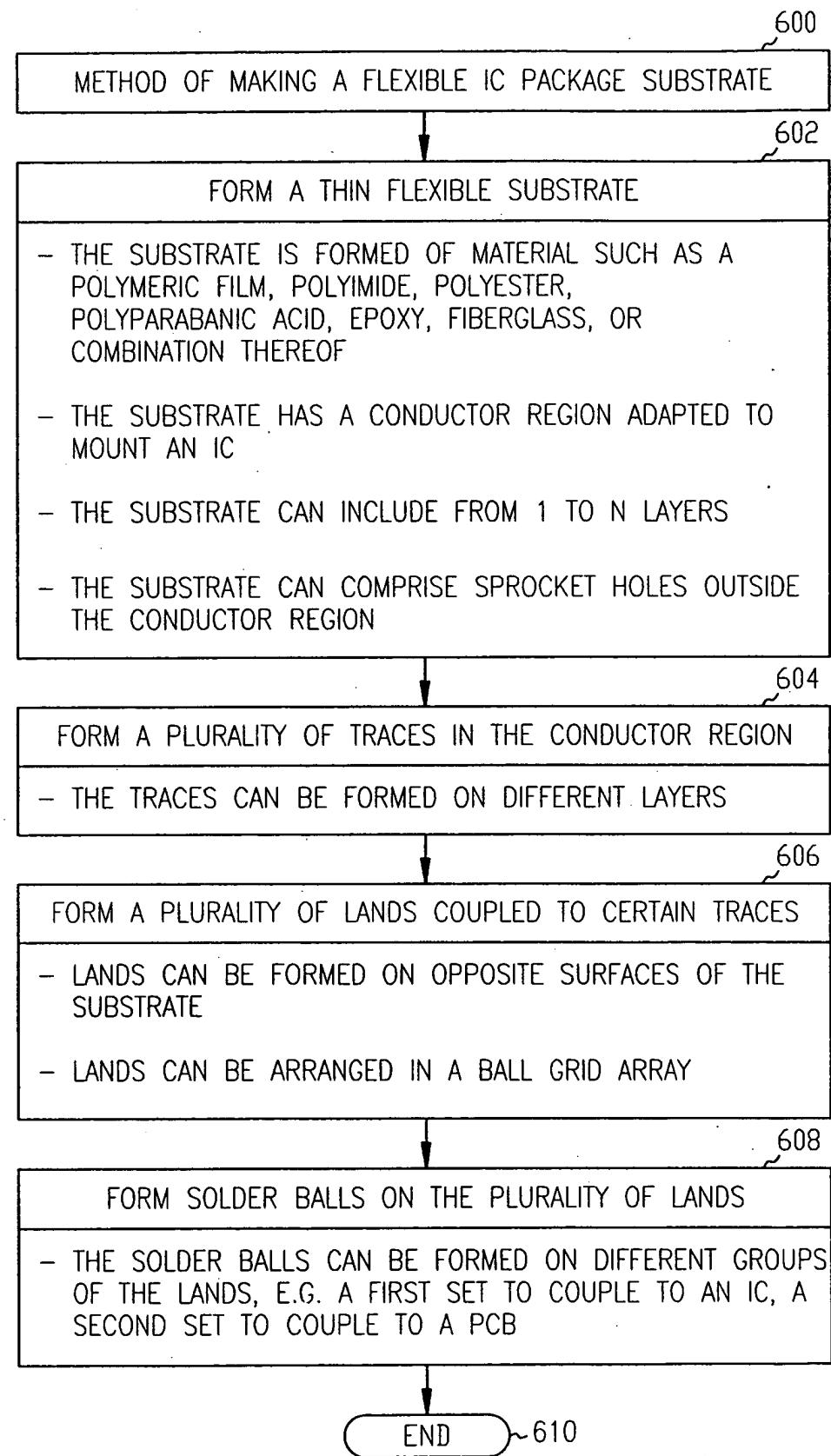


FIG. 11

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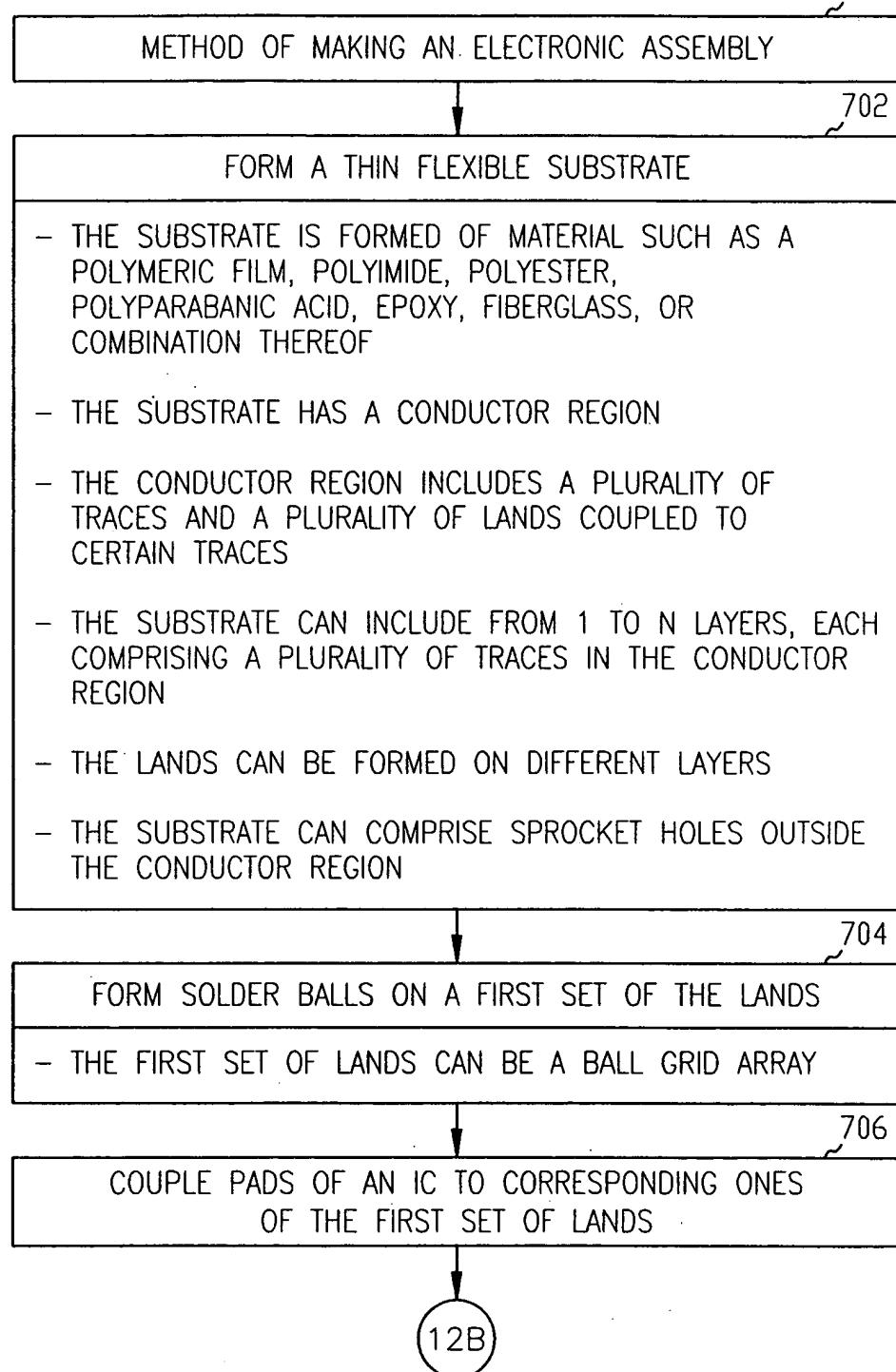


FIG. 12A

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12A

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MOUNT THE SUBSTRATE ON AN ADDITIONAL  
SUBSTRATE, E.G. A PCB

EMPLOY EITHER OR BOTH OF THE FOLLOWING:

- USE BGA BETWEEN SUBSTRATE AND PCB
  - FORM SOLDER BALLS ON A SECOND SET OF THE LANDS
  - COUPLE ONES OF THE SECOND SET OF LANDS TO CORRESPONDING TERMINALS ON THE PCB
  
- USE LEADS BETWEEN SUBSTRATE AND PCB
  - COUPLE LEADS, E.G. WIRES, BETWEEN CORRESPONDING ONES OF A THIRD SET OF LANDS AND ADDITIONAL TERMINALS OF THE PCB

END

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FIG. 12B